

IN THE SPECIFICATION:

Please amend paragraph [0002] as follows:

In microelectronic device manufacturing, a microelectronic circuit chip, or “die”, is commonly mounted to a “package” before it is integrated into a larger system. The package serves to protect the die and may provide a standardized interface between the die and the system in which it will be used. The package with the integrated die is subsequently mounted to a printed circuit board (PCB), such as a motherboard in a computer system.